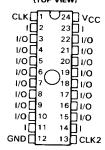
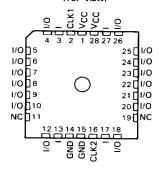
D3177, OCTOBER 1988 -- AUGUST 1989

- High-Density (Over 600 Gates)
 Replacement for TTL and 74HC
- Virtually Zero Standby Power . . . Typ 20 μA
- High Speed: Propagation Delay Time . . . 25 ns
- Asynchronous Clocking of All Registers or Banked Register Operation from 2 Synchronous Clocks
- Sixteen Macrocells with Configurable I/O Architecture Allowing for Up to 20 Inputs and 16 Outputs
- Each Output Macrocell User-Programmable for D, T, SR, or JK Flip-Flops with Individual Clear Control or Combinational Operation
- UV-Light-Erasable Cell Technology Allows for:
 - Reconfigurable Logic
 - Reprogrammable Cells
 - Full Factory Testing for 100%
 Programming Yields
- Programmable Design Security Bit Prevents Copying of Logic Stored in Device
- Advanced Software Support Featuring Schematic Capture, Interactive Netlist, Boolean Equations, and State Machine Design Entry
- Package Options Include Plastic [for One-Time-Programmable (OTP) Devices] and Ceramic Dual-In-Line Packages and Chip Carriers

DUAL-IN-LINE PACKAGE (TOP VIEW)



CHIP-CARRIER PACKAGE (TOP VIEW)



NC - No internal connection

AVAILABLE OPTIONS

		PACKAGE TYPE							
T _A RANGE	SPEED	CERAMIC DUAL-IN-LINE PACKAGE (CDIP)	CERAMIC CHIP CARRIER (CLCC)	PLASTIC† DUAL-IN-LINE PACKAGE (PDIP)	PLASTIC† CHIP CARRIER (PLCC)				
	25 ns	EP610DC-25	EP610JC-25	EP610PC-25	EP610LC-25				
0°C - 70°C	30 ns	EP610DC-30	EP610JC-30	EP610PC-30	EP610LC-30				
	35 ns	EP610DC-35	EP610JC-35	EP610PC-35	EP610LC-35				
-40°C - 85°C	40 ns	EP610DI-40	EP610JI-40	EP610PI-40	EP610LI-40				

†This package is for one-time-programmable (OTP) devices.

description

general

The Texas Instruments EP610 Erasable Programmable Logic Device is capable of implementing over 600 equivalent gates of SSI and MSI logic functions all in plastic and ceramic space-saving 24-pin, 300-mil dual-in-line (DIP) packages and 28-pin chip-carrier packages. It uses the familiar sum-of-products logic, providing a programmable AND with a fixed OR structure. The device accommodates both combinational and sequential (registered) logic functions with up to 20 inputs and 16 outputs. The EP610 has a user programmable output logic macrocell that allows each output to be configured as a combinational or registered output and feedback signals active high or active low.

A unique feature of the EP610 is the ability to program D, T, SR, or JK flip-flop operation individually for each output without sacrificing product terms. In addition, each register can be individually clocked from any of the input or feedback paths available in the AND array. These features allow a variety of logic functions to be simultaneously implemented.

The CMOS EPROM technology reduces the power consumption to less than 20% of equivalent bipolar devices without sacrificing speed performance. Erasable EPROM bits allow for enhanced factory testing. Design changes can be easily implemented by erasing the device with ultraviolet (UV) light.

Programming the EP610 is accomplished by using the TI EPLD Development System, which supports four different design entry methods. When the design has been entered, the software performs automatic translation into logical equations, Boolean minimization, and design fitting directly into an EPLD.

functional

The EP610 is an Erasable Programmable Logic Device (EPLD) that uses a CMOS EPROM technology to implement logic designs in a programmable AND logic array. The device contains a revolutionary programmable I/O architecture that provides advanced functional capability for user programmable logic.

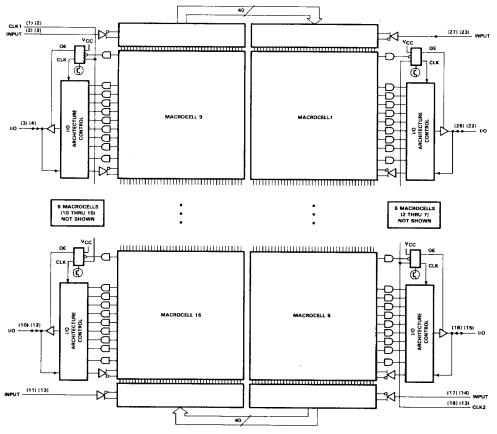
Externally, the EP610 provides 4 dedicated data inputs and 16 I/O pins, which may be configured for input, output, or bidirectional operation. Figure 1 shows the EP610 basic logic array macrocell. The internal architecture is organized with familiar sum-of-products (AND-OR) structure. Inputs to the programmable AND array come from true and complement signals from the 4 dedicated data inputs and the 16 I/O architecture-control blocks. The 40-input AND array encompasses 160 product terms, which are distributed among 16 available macrocells. Each EP610 product term represents a 40-input AND gate.

Each macrocell contains 10 product terms, 8 of which are dedicated for logic implementation. One product term is used for clear control of the macrocell internal register. The remaining product terms are used for output enable/asynchronous clock implementation.

There is an EPROM connection at the intersection point of each input signal and each product term. In the erased state, all connections are made. This means both the true and complement forms of all inputs are connected to each product term. Connections are opened during the programming process. Therefore, any product term may be connected to the true or complement form of any array input signal.



functional block diagram



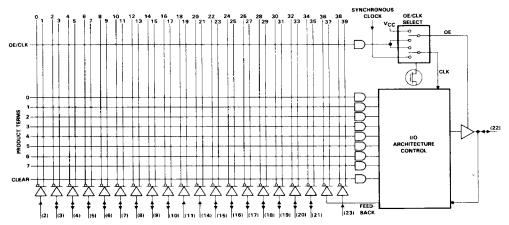
Pin numbers in () are for DIP packages; pin numbers in [] are for chip-carrier packages.

When both the true and complement forms of any signal are left intact, a logical false state results on the output of the AND gate. If both the true and complement connections are open, then a logical "don't care" applies for that input. If all inputs for the product term are programmed open, then a logical true state results on the output of the AND gate.

Two dedicated clock inputs provide synchronous clock signals to the EP610 internal registers. Each of the clock signals controls a bank of 8 registers. CLK1 controls registers associated with macrocells 9-16, and CLK2 controls registers associated with macrocells 1-8. The EP610 advanced I/O architecture allows the number of synchronous registers to be user defined, from one to sixteen. Both dedicated clock inputs are positive-edge triggered.

I/O architecture

The EP610 input/output architecture provides each macrocell with over 50 possible I/O configurations. Each I/O can be configured for combinational or registered output, with programmable output polarity. Four different types of registers (D, T, JK, and SR) can be implemented into every I/O without any additional logic requirements. I/O feedback selection can also be programmed for registered or input (pin) feedback. Another benefit of the EP610 I/O architecture is its ability to individually clock each internal register from asynchronous clock signals.



Pin numbers are for dual-in-line packages

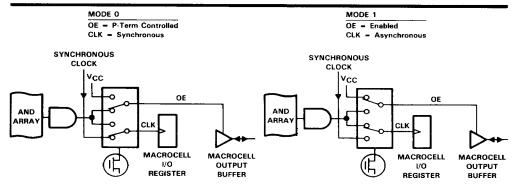
FIGURE 1. LOGIC ARRAY MACROCELL (MACROCELL 1 ILLUSTRATED)

OE/CLK selection

Figure 2 shows the two modes of operation that are provided by the OE/CLK select multiplexer. The operation of this multiplexer is controlled by a single EPROM bit and may be individually configured for each EP610 I/O pin. In Mode 0, the 3-state output buffer is controlled by a single product term. If the output of the AND gate is true, the output buffer is enabled. If the output of the AND gate is false, the output buffer is in the highimpedance state. In this mode, the macrocell flip-flop may be clocked by its respective synchronous clock input. After erasure, the OE/CLK select multiplexer is configured in Mode 0.

In Mode 1, the output-enable buffer is always enabled. The macrocell flip-flop may now be triggered from an asynchronous clock signal generated by the OE/CLK multiplexable product term. This mode allows individual clocking of flip-flops from any available signal in the AND array. Because both true and complement signals reside in the AND array, the flip-flop may be configured for positive- or negative-edge-triggered operation. With the clock now controlled by a product term, gated clock structures are also possible.





The register is clocked by the synchronous clock signal, which is common to 11 other Macrocells. The output is enabled by the logic from the product term.

The output is permanently enabled and the register is clocked via the product term. This allows for gated clocks that may be generated from elsewhere in the EP610.

FIGURE 2. OE/CLK SELECT MULTIPLEXER

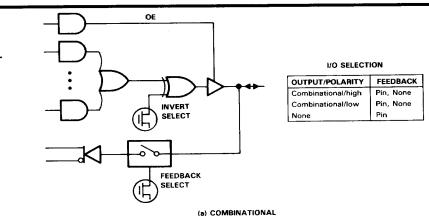
output/feedback selection

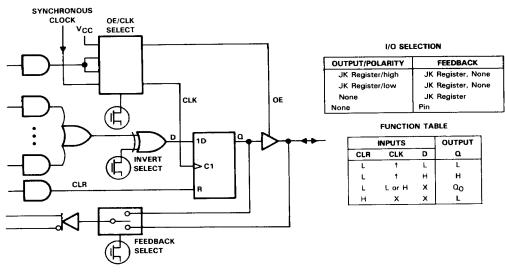
Figure 3 shows the EP610 basic output configurations. Along with combinational output, 4 register types are available. Each macrocell I/O may be independently configured. All registers have individual asynchronous clear control from a dedicated product term. When the product term is asserted, the macrocell register will immediately be loaded with a zero independently of the clock. On power-up, the EP610 performs the clear function automatically.

When the D or T register is selected, 8 product terms are ORed together and made available to the register input. The invert select EPROM bit determines output polarity. The feedback-select multiplexer enables register, I/O (pin), or no feedback to the AND array.

If the JK or SR registers are selected, the 8 product terms are shared between 2 OR gates. The allocation of product terms for each register input is optimized by the TI EPLD Development System. The invert select EPROM bit configures output polarity. The feedback-select multiplexer enables registered or no feedback to the AND array.

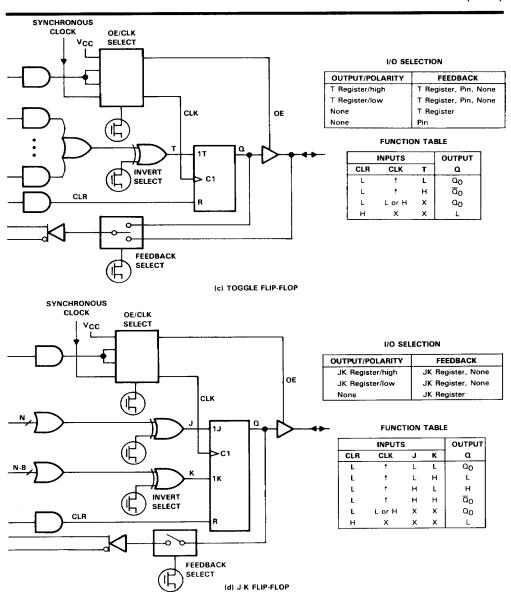
Any I/O pin may be configured as a dedicated input by selecting no output and pin feedback. No output is obtained by disabling the macrocell output buffer. In the erased state, each I/O is configured for combinational active-low output with input (pin) feedback.





(b) D-TYPE FLIP-FLOP

FIGURE 3. I/O CONFIGURATIONS







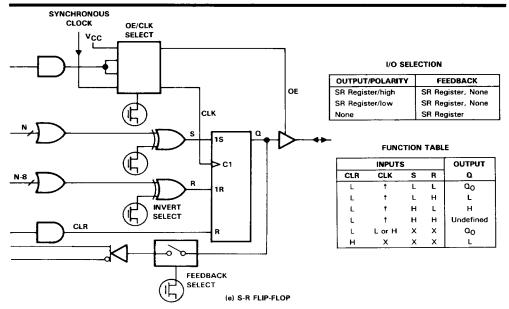


FIGURE 3. I/O CONFIGURATIONS (CONTINUED)

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, VCC (see Note 1)
Instantaneous supply voltage range, V _{CC} (t ≤ 20 ns)
Programming supply voltage range, Vpp
Instantaneous programming supply voltage range, V _{pp} (t ≤ 20 ns)2 V to 13.5 V
Input voltage range, V _I
Instantaneous input voltage range, VI (t \leq 20 ns)
VCC or GND current
Power dissipation at 25°C free-air temperature (see Note 2)
Operating free-air temperature, TA
Storage temperature range

NOTES: 1. All voltage values are with respect to GND terminal.

2. For operation above 25°C free-air temperature, derate to 120 mW at 135°C at the rate of 8.0 mW/°C.

recommended operating conditions

	PARAMETER		E	P610I	EF	P610C	
	PARAMETER		MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		4.5	5.5	4.75	5.25	٧
VI	Input voltage	0	Vcc	0	Vcc	V	
VIH				V _{CC} +0.3	2	V _{CC} +0.3	٧
VIL	Low-level input voltage (see Note 3)			0.8	-0.3	0.8	٧
Vo	Output voltage		0	Уcc	0	Vcc	٧
	Rise time	CLK input		100		250	
τr	Hise time	Other inputs		250		500	ns
	Fall time	CLK input		100		250	
tf	Other inputs			250		500	ns
TA	Operating free-air temperature	1	-40	85	0	70	°C

Note 3: The algebraic convention, in which the more negative value is designated minimum, is used in this data sheet for logic voltage levels and temperature only.

electrical charateristics over recommended operating free-air temperature range (unless otherwise noted)

						EP6101		EP610C			UNIT
	PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	MIN	TYP	MAX	UNII
.,	High-level output	TTL	I _{OH} = -4 mA		2.4			2.4			V
∨он	voltage	CMOS	IOH = -2 mA		3.84			3.84			ľ
VOL	Low-level output voltage		IOL = 4 mA				0.45			0.45	٧
l _l	Input current	ut current					±10			±10	μΑ
loz	Off-state output currer	it	VO = VCC or GND				±10			±10	μA
		Standby	VI = VCC or GND,	See Note 4		0.02	0.15		0.02	0.1	mA
lcc	Supply current	Non-turbo		See Note 5		3	15		3	10	
		Turbo	No load	See Note 5		32	75		32	60	
Ci	Input capacitance	citance $V_I = 0$, $f = 1$ MHz, $T_A = 25$		A = 25°C			20			20	pF
Co	Output capacitance		VO = 0, f = 1 MHz, TA = 25°C				20			20	рF
Cclk	Clock capacitance V		V _I = 0, f = 1 MHz, T _A = 25°C				20			20	pF

 $^{^{\}dagger}$ All typical values are at V_{CC} = 5 V, T_{A} = 25°C.

NOTES: 4. When in the non-turbo mode, the device automatically goes into the standby mode approximately 100 ns after the last transition.

5. These parameters are measured with device programmed as a 16-bit counter and f = 1 MHz.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

combinational mode, turbo bit on

PARAMETER [†]		TEST CONDITIONS	EP6	EP610-25		EP610-30		EP610-35	
		TEST CONDITIONS	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
tpd1	Input to nonregistered output			25		30		35	ns
tpd2	I/O input to nonregistered output	C _L = 35 pF		27		32		37	ns
tPZX	Input to output enable			25		30		35	ns
†PXZ	Input to output disable	C _L = 5 pF, See Note 6		25		30		35	ns
tcir	Asynchronous output clear time	C _L = 35 pF		27		32		37	ns
tio	I/O input buffer delay			2		2		2	ns

combinational mode, turbo bit off

	PARAMETER†	TEST CONDITIONS	EP610-25		EP610-30		EP610-35		UNIT
FARMETER		TEST CONDITIONS	MIN	MAX	MIN	MAX	MIN	MAX	UNII
^t pd1	Input to nonregistered output			55		60		65	กร
tpd2	I/O input to nonregistered output	C _L = 35 pF		57		62		67	ns
tPZX	Input to output enable			55		60		65	ns
†PXZ	Input to output disable	C _L = 5 pF, See Note 6		55		60		65	ns
t _{clr}	Asynchronous output clear time	C _L = 35 pF		57		62		67	กร
tio	I/O input buffer delay			2	-	2		2	ns

synchronous clock mode

PARAMETER [†]		TEST CONDITIONS	EP610-25		EP610-30		EP610-35		UNIT
		1231 CONDITIONS	MIN	MIN MAX	MIN	MAX	MIN	MAX	UNIT
fmax	Maximum frequency	See Note 7	47.6		41.7		37		MHz
t _{ca1}	Clock to output delay time			15		17		20	ns
t _{cnt}	Minimum clock period (register feedback to register output)	See Note 5		25		30		35	ns
^f cnt	Maximum frequency with feedback	See Note 5	40		33.3		28.6		MHz

asynchronous clock mode

	PARAMETERT		TEST CONDITIONS	EP610-25		EP610-30		EP610-35		
PARAMETER		TEST CONDITIONS	MIN MAX		MIN	MAX	X MIN M		UNIT	
fmax	Maximum frequency		See Note 7	47.6		41.7		37		MHz
	Clock to output delay time	Turbo bit on			27		32		37	
^t aco1		Turbo bit off			57		62		67	กร
^t acnt	Minimum clock period (register feedback to register output)				25		30		35	ns
facnt	Maximum frequency with feedback			40		33.3		28.6		MHz

[†] Letter symbols for switching characteristics and timing requirements in this data sheet have been chosen for compatibility with those used in other documentation previously prepared by another supplier for similar products. Any similarity to symbols used on other TI data sheets or to those shown in glossaries in TI data books is coincidental. The meanings may not be the same.



NOTES: 5. These parameters are measured with device programmed as a 16-bit counter and f = 1 MHz.

^{6.} This is for an output voltage change of 500 mV.

^{7.} The $f_{\mbox{max}}$ values shown represent the highest frequency of operation without feedback.

timing requirements over recommended ranges of supply voltage and free-air temperature synchronous clock mode

	PARAMETER†		TEST CONDITIONS	EP610-25		EP610-30		EP610-35		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	UNII	
t _{su}	Input setup time	Turbo bit on		21		24		27		
		Turbo bit off		51		54		57		ns
th	Input hold time			0		0		0		ns
tch	Clock high pulse duration			10		11		.12		ns
t _{cl}	Clock low pulse du	uration		10		11		12		ns

asynchronous clock mode

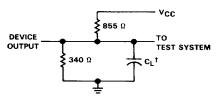
	PARAMETER†		TEST CONDITIONS	EP610-25		EP610-30		EP610-35		UNIT
PARAMETER			MIN	MAX MIN		MAX	MIN	MAX	UNII	
tasu	Input setup time	Turbo bit on		8		8		8		
		Turbo bit off		38		38		38	* * * * * * * * * * * * * * * * * * * *	ns
t _{ah}	Input hold time			12		12	-	12		ns
tach	h Clock high pulse duration			10		11		12		ns
taci	Clock low pulse duration			10		11		12		ns

[†] Letter symbols for switching characteristics and timing requirements in this data sheet have been chosen for compatibility with those used in other documentation previously prepared by another supplier for similar products. Any similarity to symbols used on other TI data sheets or to those shown in glossaries in TI data books is coincidental. The meanings may not be the same.

functional testing

The EP610 is functionally tested including complete testing of each programmable EPROM bit and all internal logic elements thus ensuring 100% programming yield. As a result, traditional problems associated with fuseprogrammed circuits are eliminated. The erasable nature of the EP610 allows test program patterns to be used and then erased.

Figure 4 shows the test circuit and the conditions under which dynamic measurements are made. Because power supply transients can affect dynamic measurements, simultaneous transitions of multiple outputs should be avoided to ensure accurate measurement. The performance of threshold tests under dynamic conditions should not be attempted. Large-amplitude fast ground-current transients normally occur as the device outputs discharge the load capacitances. These transients flowing through the parasitic inductance between the device ground terminal and the test-system ground can create significant reductions in observable input noise immunity.



†Includes jig capacitance

FIGURE 4. DYNAMIC TEST CIRCUIT

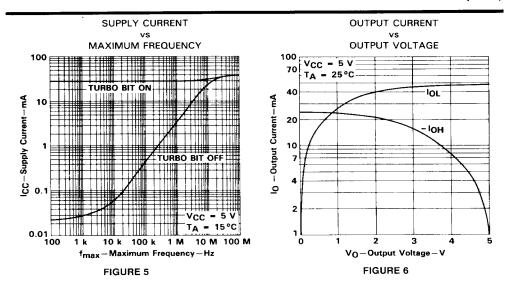
design security

The EP610 contains a programmable design security feature that controls the access to the data programmed into the device. If this programmable feature is used, a proprietary design implemented in the device cannot be copied or retrieved. This enables a high level of design control to be obtained since programmed data within the EPROM cells is invisible. The bit that controls this function, along with all other program data, may be reset by erasing the device.

turbo bit

Some EPLDs contain a programmable option to control the automatic power-down feature that enables the low-standby-power mode of the device. This option is controlled by a turbo bit that can be set using the EPLD Development System. When the turbo bit is on, the low-standby-power mode is disabled. This renders the circuit less sensitive to VCC noise transients created by the power-up/power-down cycle when operating in the low-power mode. The typical ICC versus frequency data for both the turbo-bit-on mode and the turbo-bitoff (low-power) mode is shown in Figure 5. All dynamic parameters are tested with the turbo bit on. Figure 6 shows the relationship between the output drive currents and the corresponding output voltages.





If the design requires low-power operation, the turbo bit should not be set. When operating in this mode, some dynamic parameters are subject to increases.

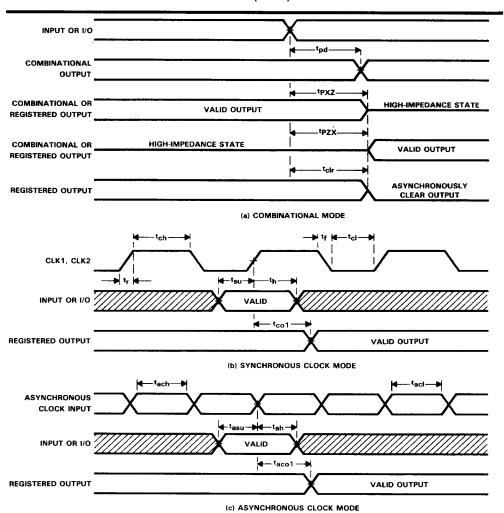
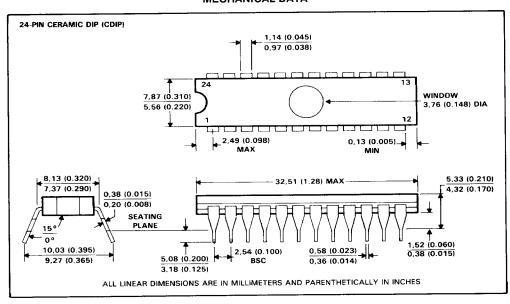
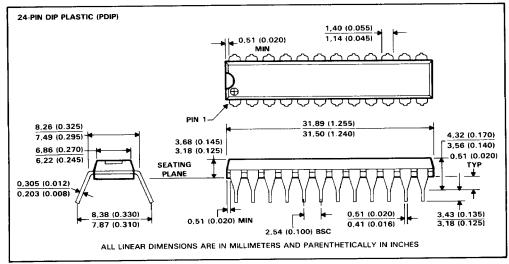


FIGURE 7. SWITCHING WAVEFORMS

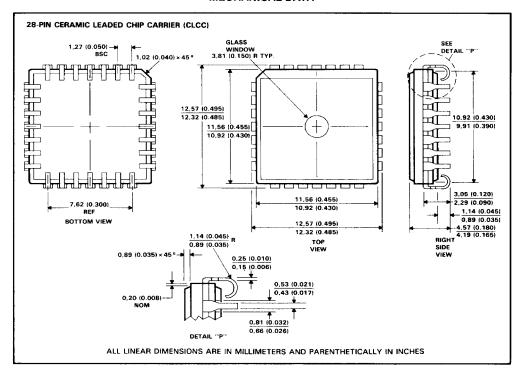


MECHANICAL DATA





MECHANICAL DATA



MECHANICAL DATA

